

## PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1  
Stylesheet Version v1.2

EPAS ID: PAT6658898

<b>SUBMISSION TYPE:</b>	NEW ASSIGNMENT
<b>NATURE OF CONVEYANCE:</b>	ASSIGNMENT
<b>CONVEYING PARTY DATA</b>	
<b>Name</b>	<b>Execution Date</b>
YAZHOU ZHANG	03/24/2021
JIANDI DU	03/23/2021
HOPE CHIU	03/30/2021
CONG ZHANG	04/07/2021
FEN YU	03/23/2021
ADA SHEN	03/30/2021
GARY ZHENG	03/23/2021
HONNY CHEN	03/23/2021
<b>RECEIVING PARTY DATA</b>	
<b>Name:</b>	WESTERN DIGITAL TECHNOLOGIES, INC.
<b>Street Address:</b>	5601 GREAT OAKS PARKWAY
<b>City:</b>	SAN JOSE
<b>State/Country:</b>	CALIFORNIA
<b>Postal Code:</b>	95119
<b>PROPERTY NUMBERS Total: 1</b>	
<b>Property Type</b>	<b>Number</b>
Application Number:	17229429
<b>CORRESPONDENCE DATA</b>	
<b>Fax Number:</b>	(215)963-5001
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
<b>Phone:</b>	2159634964
<b>Email:</b>	WDWorkGroup@morganlewis.com
<b>Correspondent Name:</b>	MICHAEL S. RYAN
<b>Address Line 1:</b>	1701 MARKET STREET
<b>Address Line 4:</b>	PHILADELPHIA, PENNSYLVANIA 19103
<b>ATTORNEY DOCKET NUMBER:</b>	058752-01-5405-US
<b>NAME OF SUBMITTER:</b>	MICHAEL S. RYAN
<b>SIGNATURE:</b>	/Michael S. Ryan/

<b>DATE SIGNED:</b>	04/15/2021
<b>Total Attachments: 2</b> source=Assignment#page1.tif source=Assignment#page2.tif	

**ASSIGNMENT**

WHEREAS, WE, **Yazhou Zhang, Jiandi Du, Hope Chiu, Cong Zhang, Fen Yu, Ada Shen, Gary Zheng and Honny Chen**, referred to here as the ASSIGNORS, are the inventors of the invention in **SEMICONDUCTOR DEVICE PACKAGE HAVING THERMALLY CONDUCTIVE LAYERS FOR HEAT DISSIPATION**, described in an application for a Patent of the United States

- ☐ which is executed on ☐ even date herewith
- ☒ which is identified by Morgan, Lewis & Bockius LLP docket no. 058752-01-5405-US
- ☐ which was filed on \_\_\_\_\_, Provisional Application No.
- ☐ which claims priority on U.S. Provisional Patent Application No(s).
- ☒ We hereby authorize and request our attorney, Michael S. Ryan, of Morgan, Lewis & Bockius LLP, to insert here in parenthesis (Application number 17/229,429, filed 4/13/2021 ) the filing date and application number of said application when known.

and WHEREAS, **WESTERN DIGITAL TECHNOLOGIES, INC.**, ASSIGNEE, having a place of business at 5601 Great Oaks Parkway, San Jose CA 95119, is desirous of obtaining our entire right, title and interest in, to and under the said invention and the said application:

NOW, THEREFORE, let it be known that for and in consideration of the sum of One Dollar (\$1.00) to me paid, and other good and valuable consideration, the receipt and sufficiency of which are hereby acknowledged, we, the said ASSIGNORS, have sold, assigned, transferred and set over, and by these presents do hereby sell, assign, transfer and set over, unto the said ASSIGNEE, its successors, legal representatives and assigns, our entire right, title and interest in, to and under the said invention, and the said United States application and all divisions, renewals and continuations thereof, and any substitute applications therefore, and all Patents of the United States which may be granted thereon and all reissues and extensions thereof; the said United States provisional patent application(s), if any, on which the said United States application claims priority; and all applications for industrial property protection, including, without limitation, all applications for patents, utility models, and designs which may hereafter be filed for said invention in any country or countries foreign to the United States, together with the right to file such applications and the right to claim for the same the priority rights derived from said United States application and said United States provisional patent application(s), if any, under the Patent Laws of the United States, the International Convention for the Protection of Industrial Property, or any other international agreement or the domestic laws of the country in which any such application is filed, as may be applicable; and all forms of industrial property protection, including, without limitation, patents, utility models, inventors' certificates and designs which may be granted for said invention in any country or countries foreign to the United States and all extensions, renewals and reissues thereof;

AND WE HEREBY authorize and request the Commissioner of Patents and Trademarks of the United States, and any Official of any country or countries foreign to the United States, whose duty it is to issue patents or other evidence or forms of industrial property protection on applications as aforesaid, to issue the same to the said ASSIGNEE, its successors, legal representatives and assigns, in accordance with the terms of this instrument.

AND WE HEREBY covenant and agree that we have full right to convey the entire interest herein assigned, and that we have not executed, and will not execute, any agreement in conflict herewith.

AND WE HEREBY further covenant and agree that we will communicate to the said ASSIGNEE, its successors, legal representatives and assigns, any facts known to us respecting said invention, and testify in any legal proceeding, sign all lawful papers, execute all divisional, continuing, reissue and foreign applications, make all rightful oaths, and generally do everything possible to aid the said ASSIGNEE, its successors, legal representatives and assigns, to obtain and enforce proper protection for said invention in all countries.

IN TESTIMONY WHEREOF, We hereunto set our hands and seals the day and year set opposite our respective signatures.

(THIS DOCUMENT MAY BE COMPLETED IN COUNTERPARTS)

Date \_\_\_\_\_  
2021年3月24日 | 8:40:42 下午 EDT DocuSigned by:  
Yazhou Zhang L.S.  
Yazhou Zhang  
F7D5889290714A9...

Date \_\_\_\_\_  
March 23, 2021 | 8:57:04 PM EDT DocuSigned by:  
Jiandi Du L.S.  
Jiandi Du  
CFB9FA478BA42D...

Date \_\_\_\_\_  
March 30, 2021 | 6:26:54 AM EDT DocuSigned by:  
Hope Chiu L.S.  
Hope Chiu  
E10E374E5A11495...

Date \_\_\_\_\_  
April 7, 2021 | 2:49:16 AM EDT DocuSigned by:  
Cong Zhang L.S.  
Cong Zhang  
88018B89F76C4FF...

Date \_\_\_\_\_  
March 23, 2021 | 9:44:04 PM EDT DocuSigned by:  
Fen Yu L.S.  
Fen Yu  
F7D5889290714A9...

Date \_\_\_\_\_  
March 30, 2021 | 1:28:29 AM EDT DocuSigned by:  
Ada Shen L.S.  
Ada Shen  
473504FC5E5B48C...

Date \_\_\_\_\_  
March 23, 2021 | 9:31:18 PM EDT DocuSigned by:  
Gary Zheng L.S.  
Gary Zheng  
414E95F71000A2...

Date \_\_\_\_\_  
March 23, 2021 | 11:44:01 PM EDT DocuSigned by:  
Honny Chen L.S.  
Honny Chen  
4E6AC6F7B1544AF...